



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2021-07-30
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9691-TR	N960*UR7SCAP	A	959	2021-07-30
	Amount	UoM	Unit type	ST ECOPACK Grade
	520	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00799564	

Package Designator	Package Size	Nbr of instances	Shape	
Not Applicable	14.00,14.00,1.00	128	0	
Comment	TQFP 128 14x14x1.0 1.0 ExpadDown. MDF valid for CPs: L9691,L9691-TR			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 19th March 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.31	die - leadframe	604

QueryList : REACH-8th July 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Cobalt, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	N960*UR75CAP					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	45.437	mg	supplier	die	Silicon(Si)	7440-21-3		41.159	mg	905847	79152
				supplier	metallisation	Copper(Cu)	7440-50-8		2.805	mg	61734	5394
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.004	mg	88	8
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.314	mg	6911	604
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.099	mg	2179	190
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.003	mg	66	6
				supplier	metallisation	Tungsten(W)	7440-33-7		0.130	mg	2861	250
				supplier	passivation	Silicon oxide	7631-86-9		0.449	mg	9882	863
				supplier	polymer coating	polyimide	proprietary		0.474	mg	10432	912
Leadframe	M-004 Copper and its alloys	196.800	mg	supplier	alloy	Copper(Cu)	7440-50-8		187.208	mg	951259	360015
				supplier	alloy	Iron(Fe)	7439-89-6		4.403	mg	22373	8467
				supplier	alloy	Iron phosphide	1310-43-6		0.265	mg	1347	510
				supplier	alloy	Zinc(Zn)	7440-66-6		0.231	mg	1174	444
				supplier	tape	Polyimide film	proprietary		2.346	mg	11921	4512
				supplier	tape	Polyethylene-terephthalate film	proprietary		1.595	mg	8105	3067
				supplier	tape	Acrylonitrilebutadiene rubber	proprietary		0.282	mg	1433	542
				supplier	tape	Bismaleimide	proprietary		0.235	mg	1194	452
				supplier	tape	Phenol type resin	proprietary		0.235	mg	1194	452
Die attach	M-011 Other inorganic materials	6.162	mg	supplier	glue	Silver(Ag)	7440-22-4		5.496	mg	891918	10569
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.462	mg	74976	888
				supplier	glue	Bismaleimide resin	proprietary		0.185	mg	30023	356
				supplier	glue	Epoxy-cyclohexylethyltrimethoxysilane	3388-04-3		0.019	mg	3083	37
Bonding wires	M-004 Copper and its alloys	2.848	mg	supplier	wire	Copper(Cu)	7440-50-8		2.848	mg	1000000	5477
Encapsulation	M-011 Other inorganic materials	262.148	mg	supplier	mold compound	Silica vitreous	60676-86-0		213.520	mg	814501	410615
				supplier	mold compound	Silicon oxide	7631-86-9		19.661	mg	75000	37810
				supplier	mold compound	Epoxy type resin	proprietary		19.661	mg	75000	37810
				supplier	mold compound	Phenol type resin	proprietary		7.864	mg	29998	15123
				supplier	mold compound	Carbon black	1333-86-4		1.442	mg	5501	2773
Connections coating	Solder	6.605	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.605	mg	1000000	12702